### ■Minimum Bus Cycle

• 83.3ns (CF=12MHz)

Note: The bus cycle time here refers to the ROM read speed.

#### ■Minimum Instruction Cycle Time

• 250ns (CF=12MHz)

#### Ports

• I/O ports	
Ports whose I/O direction can be designated in 1 bit units	28 (P10 to P17, P20 to P27, P30 to P34,
	P70 to P73, PWM0, PWM1, XT2)
Ports whose I/O direction can be designated in 4 bit units	8 (P00 to P07)
• USB ports	2 (D+, D-)
<ul> <li>Dedicated oscillator ports</li> </ul>	2 (CF1, CF2)
• Input-only port (also used for oscillation)	1 (XT1)
• Reset pins	$1 (\overline{\text{RES}})$
• Power pins	6 (VSS1 to 3, VDD1 to 3)

#### ■Timers

- Timer 0: 16-bit timer/counter with a capture register.
  - Mode 0: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register)  $\times 2$  channels
  - Mode 1: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register) + 8-bit counter (with an 8-bit capture register)
  - Mode 2: 16-bit timer with an 8-bit programmable prescaler (with a 16-bit capture register)
  - Mode 3: 16-bit counter (with a 16-bit capture register)
- Timer 1: 16-bit timer/counter that supports PWM/toggle outputs
  - Mode 0: 8-bit timer with an 8-bit prescaler (with toggle outputs)
    - + 8-bit timer/counter with an 8-bit prescaler (with toggle outputs)
  - Mode 1: 8-bit PWM with an-8bit prescaler  $\times$  2 channels
  - Mode 2: 16-bit timer/counter with an 8-bit prescaler (with toggle outputs)
    - (toggle outputs also possible from the lower-order 8 bits)
  - Mode 3: 16-bit timer with an 8-bit prescaler (with toggle outputs)
    - (The lower-order 8 bits can be used as PWM.)
- Timer 6: 8-bit timer with a 6-bit prescaler (with toggle output)
- Timer 7: 8-bit timer with a 6-bit prescaler (with toggle output)
- Base timer
  - 1) The clock is selectable from the subclock (32.768kHz crystal oscillation), system clock, and timer 0 prescaler output.
  - 2) Interrupts programmable in 5 different time schemes

#### ■SIO

- SIO0: Synchronous serial interface
  - 1) LSB first/MSB first mode selectable
  - 2) Transfer clock cycle: 4/3 to 512/3 tCYC
  - 3) Automatic continuous data transmission (1 to 256 bits, specifiable in 1 bit units, suspension and resumption of data transmission possible in 1 byte units)
- SIO1: 8-bit asynchronous/synchronous serial interface
- Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clocks)
- Mode 1: Asynchronous serial I/O (half-duplex, 8 data bits, 1 stop bit, 8 to 2048 tCYC baudrates)
- Mode 2: Bus mode 1 (start bit, 8 data bits, 2 to 512 tCYC transfer clocks)
- Mode 3: Bus mode 2 (start detect, 8 data bits, stop detect)
- SIO4: Synchronous serial interface
  - 1) LSB first/MSB first mode selectable
  - 2) Transfer clock cycle: 4/3 to 1020/3 tCYC
  - 3) Automatic continuous data transmission (1 to 2048 bytes, specifiable in 1 byte units, suspension and resumption of data transmission possible in 1 byte or 2 bytes units)
  - 4) Auto-start-on-falling-edge function
  - 5) Clock polarity selectable
  - 6) CRC16 calculator circuit built in

#### ■Full Duplex UART

- 1) Data length: 7/8/9 bits selectable
- 2) Stop bits: 1 bit (2 bits in continuous transmission mode)
- 3) Baud rate: 16/3 to 8192/3 tCYC
- ■AD Converter: 12 bits × 12 channels
  - 12-/8-bit resolution selectable AD converter
  - Reference-voltage automatic generation control
- ■PWM: Multifrequency 12-bit PWM × 2 channels

■Infrared Remote Controller Receiver Circuit

- 1) Noise rejection function (noise filter time constant: Approx. 120µs when the 32.768kHz crystal oscillator is selected as the reference voltage source)
- 2) Supports data encoding systems such as PPM (Pulse Position Modulation) and Manchester encoding
- 3) X'tal HOLD mode release function

■USB Interface (function controller)

- Compliant with USB 2.0 Full-Speed
- Supports a maximum of 4 user-defined endpoints.

Endpoint		EP0	EP1	EP2	EP3	EP4
Transfer	Control	0	-	-	-	-
Туре	Bulk	-	0	0	0	0
	Interrupt	-	0	0	0	0
	Isochronous	-	0	0	0	0
Max. paylo	bad	64	64	64	64	64

■Watchdog Timer

- External RC watchdog timer
- Interrupt and reset signals selectable
- Clock Output Function
  - 1) Able to output selected oscillation clock 1/1, 1/2, 1/4, 1/8, 1/16, 1/32, 1/64 as system clock.
  - 2) Able to output oscillation clock of sub clock.

#### ■Interrupts

- 28 sources, 10 vector addresses
  - 1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt requests of the level equal to or lower than the current interrupt are not accepted.
  - 2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the smallest vector address takes precedence.

No.	Vector Address	Level	Interrupt Source
1	00003H	X or L	INT0
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L/INT4/USB bus active/Remote control receive
4	0001BH	H or L	INT3/INT5/base timer
5	00023H	H or L	тон
6	0002BH	H or L	T1L/T1H
7	00033H	H or L	SIO0/USB bus reset/USB suspend/UART1 receive
8	0003BH	H or L	SIO1/USB endpoint/USB-SOF/SIO4/UART1 transmit
9	00043H	H or L	ADC/T6/T7
10	0004BH	H or L	Port 0/PWM0/PWM1

<sup>•</sup> Priority Level: X > H > L

Subroutine Stack Levels: 1024 levels (the stack is allocated in RAM.)

■High-speed Multiplication/Division Instructions

- 16 bits  $\times$  8 bits (5 tCYC execution time)
- 24 bits  $\times$  16 bits (12 tCYC execution time)
- 16 bits ÷ 8 bits (8 tCYC execution time)
- 24 bits  $\div$  16 bits (12 tCYC execution time)

#### ■Oscillation Circuits

- RC oscillation circuit (internal): For system clock
- CF oscillation circuit: For system clock
- Crystal oscillation circuit: For system clock, time-of-day clock
- PLL circuit (internal): For USB interface (see Fig.5)

#### ■Standby Function

- HALT mode: Halts instruction execution while allowing the peripheral circuits to continue operation.
  - 1) Oscillation is not halted automatically.
  - 2) Canceled by a system reset or occurrence of an interrupt.
- HOLD mode: Suspends instruction execution and the operation of the peripheral circuits.
  - 1) The PLL base clock generator, CF, RC and crystal oscillators automatically stop operation.
  - 2) There are four ways of resetting the HOLD mode.
  - (1) Setting the reset pin to the lower level.
  - (2) Setting at least one of the INTO, INT1, INT2, INT4, and INT5 pins to the specified level
  - (3) Having an interrupt source established at port 0
  - (4) Having an bus active interrupt source established in the USB interface circuit
- X'tal HOLD mode: Suspends instruction execution and the operation of the peripheral circuits except for reception of a remote control signal.
  - 1) The PLL base clock generator, CF and RC oscillator automatically stop operation.
  - 2) The state of crystal oscillation established when the X'tal HOLD mode is entered is retained.
  - 3) There are six ways of resetting the X'tal HOLD mode.
    - (1) Setting the reset pin to the low level
    - (2) Setting at least one of the INTO, INT1, INT2, INT4, and INT5 pins to the specified level
    - (3) Having an interrupt source established at port 0
    - (4) Having an interrupt source established in the base timer circuit
    - (5) Having an bus active interrupt source established in the USB interface circuit
    - (6) Having an interrupt source established in the infrared remote controller receiver circuit.

<sup>•</sup> Of interrupts of the same level, the one with the smallest vector address takes precedence.

### ■Development Tools

• On-chip debugger: TCB87 type-B + LC87F1A32A

#### ■Flash ROM Programming Boards

Package	Programming boards
SQFP48(7×7)	W87F55256SQ

#### ■Recommended EPROM Programmer

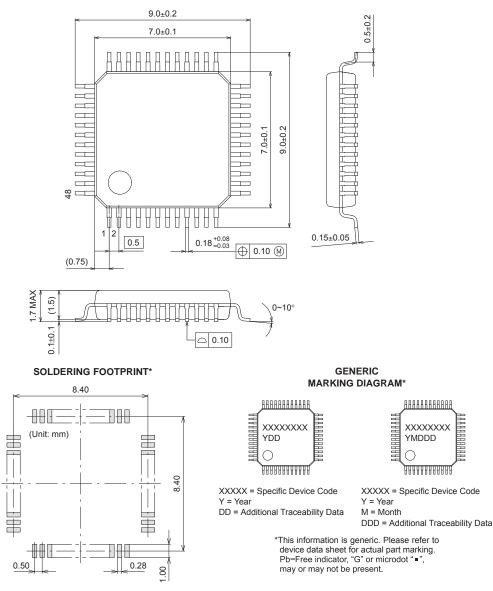
Maker	Maker Model		Device	
Flash Support Group, Inc.	AF9708/AF9709/AF9709B	After Rev02.73	LC87F1A32A	
(Single)	(including product of Ando Electric Co., Ltd.)	Alter Rev02.75	EC67FTA3ZA	
		Application Version: After 1.03		
Our company	SKK (SanyoFWS)	Chip Data Version: After 2.07	LC87F1A32	

### **Package Dimensions**

unit : mm





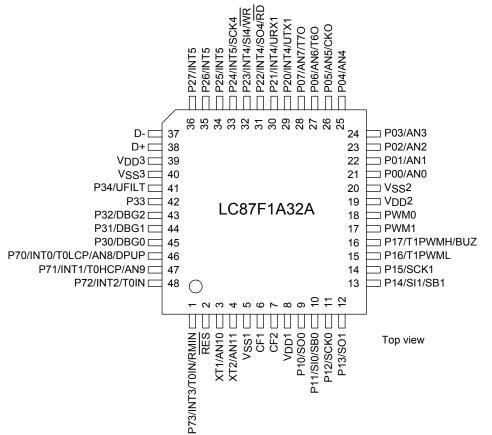


NOTE: The measurements are not to guarantee but for reference only.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Downloaded from Arrow.com.

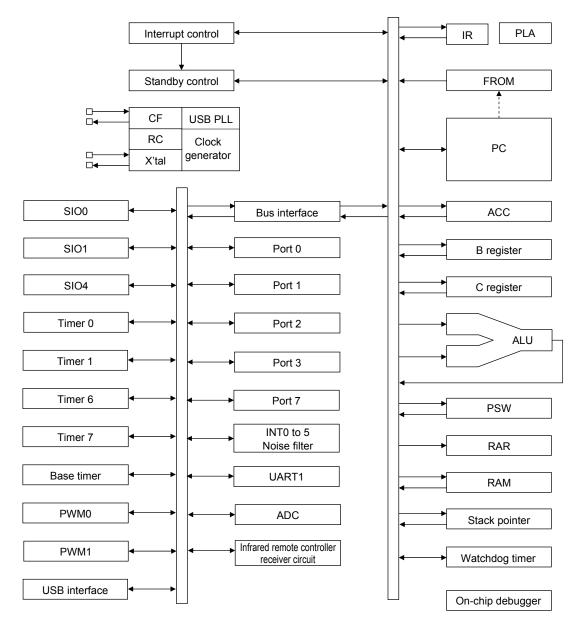
### **Pin Assignment**



#### SQFP48(7×7) "Lead-free Type"

SQFP48	NAME	SQFP48	NAME
1	P73/INT3/T0IN/RMIN	25	P04/AN4
2	RES	26	P05/AN5/CKO
3	XT1/AN10	27	P06/AN6/T6O
4	XT2/AN11	28	P07/AN7/T7O
5	V <sub>SS</sub> 1	29	P20/INT4/UTX1
6	CF1	30	P21/INT4/URX1
7	CF2	31	P22/INT4/SO4/RD
8	V <sub>DD</sub> 1	32	P23/INT4/SI4/WR
9	P10/SO0	33	P24/INT5/SCK4
10	P11/SI0/SB0	34	P25/INT5
11	P12/SCK0	35	P26/INT5
12	P13/SO1	36	P27/INT5
13	P14/SI1/SB1	37	D-
14	P15/SCK1	38	D+
15	P16/T1PWML	39	V <sub>DD</sub> 3
16	P17/T1PWMH/BUZ	40	V <sub>SS</sub> 3
17	PWM1	41	P34/UFILT
18	PWM0	42	P33
19	V <sub>DD</sub> 2	43	P32/DBGP2
20	V <sub>SS</sub> 2	44	P31/ DBGP1
21	P00/AN0	45	P30/ DBGP0
22	P01/AN1	46	P70/INT0/T0LCP/AN8/DPUP
23	P02/AN2	47	P71/INT1/T0HCP/AN9
24	P03/AN3	48	P72/INT2/T0IN

# System Block Diagram



# **Pin Description**

Pin Name	I/O				Description			Option
V <sub>SS</sub> 1,	-	- power suppl	y pin					No
V <sub>SS</sub> 2,								
V <sub>SS</sub> 3								
V <sub>DD</sub> 1,	-	+ power supp	ly pin					No
V <sub>DD</sub> 2								
V <sub>DD</sub> 3	-	USB referenc	e voltage pin					Yes
Port 0	I/O	• 8-bit I/O por	t					Yes
P00 to P07		<ul> <li>I/O specifiab</li> </ul>	ole in 4-bit units					
		Pull-up resis	stors can be tur	ned on and off i	n 4-bit units.			
		HOLD reset	input					
		Port 0 interre	upt input					
		Pins function	ns					
		AD converte	er input port: AN	10 to AN7 (P00	to P07)			
		P05: Systen	n Clock Output					
		P06: Timer	6 toggle outputs	3				
			7 toggle outputs	3				
Port 1	I/O	8-bit I/O por	t					Yes
P10 to P17			ole in 1-bit units					
			stors can be tur	ned on and off i	n 1-bit units.			
		Pin functions						
		P10: SIO0 d						
			lata input/bus I/	0				
		P12: SIO0 c						
		P13: SIO1 d	-	_				
			lata input/bus I/	0				
		P15: SIO1 c						
			1 PWML output					
Dart 0	1/0		1 PWMH outpu	beeper output				 Var
Port 2	I/O	8-bit I/O por						Yes
P20 to P27			ble in 1-bit units stors can be turi	od on and off i	n 1 hit unite			
		Pin functions			IT I-DIL UTILS.			
				D reset input/t	imer 1 event inp	ut/timer 0L cant	ture input/	
		1 20 10 1 20.	timer 0H captu	-				
		P24 to P27	-	-	imer 1 event inp	ut/timer 0L capt	ture input/	
			timer 0H captu	-				
		P20: UART	-					
		P21: UART	1 receive					
		P22: SIO4 d	late I/O/parallel	interface RD o	utput			
			late I/O/parallel					
		P24: SIO4 c						
		Interrupt ack	knowledge type					
			Rising	Falling	Rising & Falling	H level	L level	
		INT4	enable	enable	enable	disable	disable	
		INT5	enable	enable	enable	disable	disable	

Continued on next page.

Pin Name	I/O			C	Description				Option
Port 3	I/O	• 5-bit I/O po	• 5-bit I/O port						Yes
P30 to P34		<ul> <li>I/O specifia</li> </ul>	ble in 1-bit units						
		Pull-up resi	stors can be turi	ned on and off ir	1-bit units.				
		<ul> <li>Pin function</li> </ul>	S						
		P34: USB ii	nterface PLL filte	er pin (see Fig.5	)				
		Onchip deb	ugger pin: DBG	P0 to DBGP2 (P	30 to P32)				
Port 7	I/O	• 4-bit I/O po							No
P70 to P73			ble in 1-bit units						
				ned on and off ir	1-bit units.				
		<ul> <li>Pin function</li> </ul>							
				t input/timer 0L	capture input/wa	atchdog timer ou	itput/		
			ikΩ pull-up resis						
			-	t input/timer 0H		<b>.</b>			
				t input/timer 0 e	vent input/timer	OL capture inpu	t/		
		-	peed clock cour	a noise filter)/tim	ar 0 avant innut	/ timer Oll cont	ina inaut/		
				ller receiver inp			ire iriput		
				•					
			AD converter input port: AN8(P70), AN9(P71) Interrupt acknowledge type						
			knowledge type		Rising &				
			Rising	Falling	Falling	H level	L level		
		INT0	enable	enable	disable	enable	enable		
		INT1	enable	enable	disable	enable	enable		
		INT2	enable	enable	enable	disable	disable		
		INT3	enable	enable	enable	disable	disable		
		11113	enable	enable	enable	disable	disable		
PWM0	I/O	• PWM0 and	PWM1 output p	ort					No
PWM1		• General-pu	rpose input port						
D-	I/O	• USB data I/	O pin D-						No
		General-pu	rpose I/O port						
D+	I/O	• USB data I/	O pin D+						No
		General-pu	rpose I/O port						
RES	Input	Reset pin							No
XT1	Input	32.768kHz crystal oscillator input pin							No
		Pin function	S						
		General-pu	rpose input port						
		AD convert	er input port: AN	10					
		Must be con	nected to V <sub>DD</sub> 1	if not to be used	l.				
XT2	I/O	32.768kHz c	ystal oscillator o	output pin					No
		Pin functions     General-purpose I/O port							
			er input port: AN						
				d kept open if no	ot to be used.				
CF1	Input	Ceramic reso	onator input pin						No
CF2	Output	Ceramic reso	nator output pir	1					No

### **Port Output Types**

The table below lists the types of port outputs and the presence/absence of a pull-up resistor. Data can be read into any input port even if it is in the output mode.

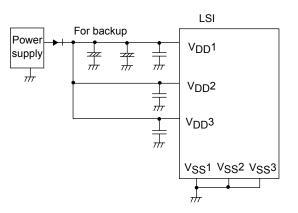
Port Name	Option Selected in Units of	Option Type	Output Type	Pull-up Resistor
P00 to P07	1 bit	1	CMOS	Programmable (Note 1)
		2	Nch-open drain	No
P10 to P17	1 bit	1	CMOS	Programmable
P20 to P27 P30 to P34		2	Nch-open drain	Programmable
P70	-	No	Nch-open drain	Programmable
P71 to P73	-	No	CMOS	Programmable
PWM0, PWM1	-	No	CMOS	No
D+, D-	-	No	CMOS	No
XT1	-	No	Input only	No
XT2	-	No	32.768kHz crystal oscillator output (Nch-open drain when in general-purpose output mode)	No

Note 1: Programmable pull-up resistors for port 0 are controlled in 4 bit units (P00 to 03, P04 to 07).

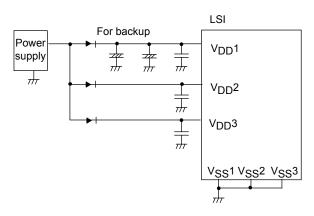
### **Power Pin Treatment**

Connect the IC as shown below to minimize the noise input to the  $V_{DD1}$  pin. Be sure to electrically short the  $V_{SS1}$ ,  $V_{SS2}$ , and  $V_{SS3}$  pins.

Example 1: When the microcontroller is in the backup state in the HOLD mode, the power to sustain the high level of output ports is supplied by their backup capacitors.



Example 2: The high level output at ports is not sustained and unstable in the HOLD backup mode.



### **USB** Reference Power Option

When a voltage 4.4 to 5.5V is supplied to  $V_{DD1}$  and the internal USB reference voltage circuit is activated, the reference voltage for USB port output is generated. The active/inactive state of reference voltage circuit can be switched by the option select. The procedure for marking the option selection is described below.

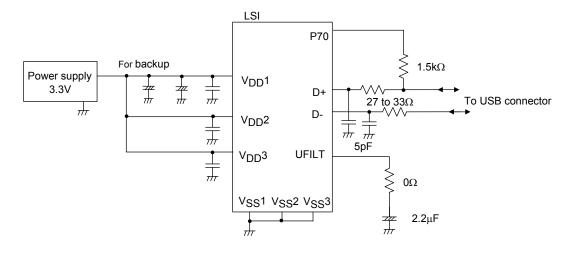
		(1)	(2)	(3)	(4)
Option select	USB Regulator	USE	USE	USE	NONUSE
	USB Regulator at HOLD mode	USE	NONUSE	NONUSE	NONUSE
	USB Regulator at HALT mode	USE	NONUSE	USE	NONUSE
Reference voltage circuit	Normal state	active	active	active	inactive
state	HOLD mode	active	inactive	inactive	inactive
	HALT mode	active	inactive	active	inactive

• When the USB reference voltage circuit is made inactive, the level of the reference voltage for USB port output is equal to V<sub>DD</sub>1.

- Selection (2) or (3) can be used to set the reference voltage circuit inactive in HOLD or HALT mode.
- When the reference voltage circuit is activated, the current drain increase by approximately 100µA compared with when the reference voltage circuit is inactive.

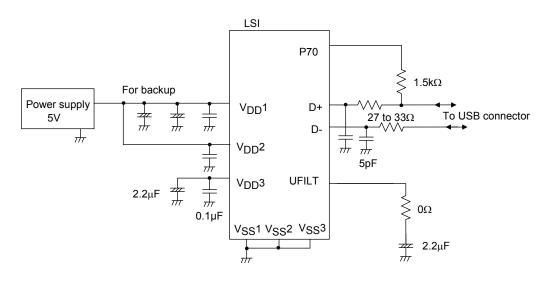
Example 1: VDD1=VDD2=3.3V

- Inactivating the reference voltage circuit (selection (4)).
- Connecting  $V_{DD}3$  to  $V_{DD}1$  and  $V_{DD}2$ .



Example 2: V<sub>DD</sub>1=V<sub>DD</sub>2=5.0V

- Activating the reference voltage circuit (selection (1)).
- Isolating VDD3 from VDD1 and VDD2, and connecting capacitor between VDD3 and VSS.



	Parameter	Symbol	Pin/Remarks	Conditions			Speci	fication	
	Farameter	Symbol	FINITEINAIRS	Conditions	V <sub>DD</sub> [V]	min	typ	max	uni
	iximum supply tage	V <sub>DD</sub> max	V <sub>DD</sub> 1, V <sub>DD</sub> 2, V <sub>DD</sub> 3	V <sub>DD</sub> 1=V <sub>DD</sub> 2=V <sub>DD</sub> 3		-0.3		+6.5	
Input voltage		V <sub>I</sub> (1)	XT1, CF1			-0.3		V <sub>DD</sub> +0.3	V
Input/output voltage Peak output current		V <sub>IO</sub> (1)	Ports 0, 1, 2, 3, 7 PWM0, PWM1, XT2			-0.3		V <sub>DD</sub> +0.3	
	-	IOPH(1)	Ports 0, 1, 2	When CMOS output type is selected     Per 1 applicable pin		-10			
		IOPH(2)	PWM0, PWM1	Per 1 applicable pin		-20			
		IOPH(3)	Ports 3 P71 to P73	When CMOS output type is selected     Per 1 applicable pin		-5			
current	Average output current	IOMH(1)	Ports 0, 1, 2	When CMOS output type is selected     Per 1 applicable pin		-7.5			
Itput	(Note 1-1)	IOMH(2)	PWM0, PWM1	Per 1 applicable pin		-15			
High level output current		IOMH(3)	Ports 3 P71 to P73	When CMOS output type is selected     Per 1 applicable pin		-3			
Ξ	Total output	ΣIOAH(1)	Ports 0, 2	Total of all applicable pins		-25			
	current	ΣIOAH(2)	Port 1 PWM0, PWM1	Total of all applicable pins		-25			
		ΣIOAH(3)	Ports 0, 1, 2 PWM0, PWM1	Total of all applicable pins		-45			
		ΣIOAH(4)	Ports 3 P71 to P73	Total of all applicable pins		-10			m/
		ΣIOAH(5)	D+, D-	Total of all applicable pins		-25			
	Peak output current	IOPL(1)	P02 to P07 Ports 1, 2 PWM0, PWM1	Per 1 applicable pin				20	
		IOPL(2)	P00, P01	Per 1 applicable pin				30	
		IOPL(3)	Ports 3, 7, XT2	Per 1 applicable pin				10	
tput current	Average output current	IOML(1)	P02 to P07 Ports 1, 2 PWM0, PWM1	Per 1 applicable pin				15	
utpr	(Note 1-1)	IOML(2)	P00, P01	Per 1 applicable pin				20	
Low level ou		IOML(3)	Ports 3, 7, XT2	Per 1 applicable pin				7.5	
w le	Total output	$\Sigma IOAL(1)$	Ports 0, 2	Total of all applicable pins				45	
Lo	current	ΣIOAL(2)	Port 1 PWM0, PWM1	Total of all applicable pins				45	
		ΣIOAL(3)	Ports 0, 1, 2 PWM0, PWM1	Total of all applicable pins				80	
		$\Sigma IOAL(4)$	Ports 3, 7, XT2	Total of all applicable pins				15	
		ΣIOAL(5)	D+, D-	Total of all applicable pins				25	
	owable power ssipation	Pd max	SQFP48(7×7)	Ta=-30to+70°C				190	m∖
	erating ambient mperature	Topr				-30		+70	
Sto	orage ambient	Tstg				-55		+125	°C

Note 1-1: The mean output current is a mean value measured over 100ms.

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Parameter	Symbol	Pin/Remarks	Conditions			Specific	ation	
Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	uni
Operating	V <sub>DD</sub> (1)	V <sub>DD</sub> 1=V <sub>DD</sub> 2=V <sub>DD</sub> 3	$0.245 \mu s \leq tCYC \leq 200 \mu s$		3.0		5.5	
supply voltage (Note 2-1)			$0.245 \mu s \le tCYC \le 0.383 \mu s$ USB circuit operation mode		3.0		5.5	
			$0.490 \mu s \le tCYC \le 200 \mu s$ Except for onboard programming		2.7		5.5	
Memory sustaining supply voltage	VHD	V <sub>DD</sub> 1=V <sub>DD</sub> 2=V <sub>DD</sub> 3	RAM and register contents sustained in HOLD mode.		2.0		5.5	
High level input voltage	V <sub>IH</sub> (1)	Ports 0, 1, 2, 3 P71 to P73 P70 port input/ interrupt side PWM0, PWM1		2.7 to 5.5	0.3V <sub>DD</sub> +0.7		V <sub>DD</sub>	
	V <sub>IH</sub> (2)	Port 70 watchdog timer side		2.7 to 5.5	0.9V <sub>DD</sub>		V <sub>DD</sub>	V
	V <sub>IH</sub> (3)	XT1, XT2, CF1, RES		2.7 to 5.5	0.75V <sub>DD</sub>		V <sub>DD</sub>	
Low level input voltage	V <sub>IL</sub> (1)	Ports 1, 2, 3 P71 to P73		4.0 to 5.5	V <sub>SS</sub>		0.1V <sub>DD</sub> +0.4	
	V <sub>IL</sub> (2)	P70 port input/ interrupt side		2.7 to 4.0	V <sub>SS</sub>		0.2V <sub>DD</sub>	
	V <sub>IL</sub> (3)	Port 0 PWM0, PWM1		4.0 to 5.5	V <sub>SS</sub>		0.15V <sub>DD</sub> +0.4	
	V <sub>IL</sub> (4)			2.7 to 4.0	V <sub>SS</sub>		0.2V <sub>DD</sub>	
	V <sub>IL</sub> (5)	Port 70 watchdog timer side		2.7 to 5.5	V <sub>SS</sub>		0.8V <sub>DD</sub> -1.0	
	V <sub>IL</sub> (6)	XT1, XT2, CF1, RES		2.7 to 5.5	V <sub>SS</sub>		0.25V <sub>DD</sub>	
Instruction	tCYC			3.0 to 5.5	0.245		200	
cycle time (Note 2-2)			Except for onboard programming	2.7 to 5.5	0.490		200	μS
External system clock frequency	FEXCF(1)	CF1	<ul> <li>CF2 pin open</li> <li>System clock frequency division ratio=1/1</li> <li>External system clock duty =50±5%</li> </ul>	3.0 to 5.5	0.1		12	N.41 I
			<ul> <li>CF2 pin open</li> <li>System clock frequency division ratio=1/1</li> <li>External system clock duty =50±5%</li> </ul>	2.7 to 5.5	0.1		6	МН
Oscillation frequency	FmCF(1)	CF1, CF2	12 MHz ceramic oscillation See Fig. 1.	3.0 to 5.5		12		
range (Note 2-3)	FmCF(2)	CF1, CF2	6 MHz ceramic oscillation See Fig. 1.	2.7 to 5.5		6		MH
	FmRC		Internal RC oscillation	2.7 to 5.5	0.3	1.0	2.0	
	FsX'tal	XT1, XT2	32.768kHz crystal oscillation See Fig. 2.	2.7 to 5.5		32.768		kH:

### Allowable Operating Conditions at Ta = -30 °C to +70 °C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0$ V

Note 2-1: V<sub>DD</sub> must be held greater than or equal to 3.0V in the flash ROM onboard programming mode. Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.

Note 2-3: See Tables 1 and 2 for the oscillation constants.

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

Descentes	O: male al	Dia (Damarka	Candiliana			Specificat	ion	
Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
High level input current	I <sub>IH</sub> (1)	Ports 0, 1, 2, 3 Port 7 RES PWM0, PWM1 D+, D-	Output disabled Pull-up resistor off VIN=VDD (Including output Tr's off leakage current)	2.7 to 5.5			1	
	I <sub>IH</sub> (2)	XT1, XT2	For input port specification VIN <sup>=V</sup> DD	2.7 to 5.5			1	
	I <sub>IH</sub> (3)	CF1	V <sub>IN</sub> =V <sub>DD</sub>	2.7 to 5.5			15	μA
Low level input current	IIL(1)	Ports 0, 1, 2, 3 Port 7 RES PWM0, PWM1 D+, D-	Output disabled Pull-up resistor off VIN=VSS (Including output Tr's off leakage current)	2.7 to 5.5	-1			. μΑ
	I <sub>IL</sub> (2)	XT1, XT2	For input port specification	2.7 to 5.5	-1			
	I <sub>IL</sub> (3)	CF1	VIN=VSS	2.7 to 5.5	-15			
High level output voltage	V <sub>OH</sub> (1)	Ports 0, 1, 2, 3	I <sub>OH</sub> =-1mA	4.5 to 5.5	V <sub>DD</sub> -1			
	V <sub>OH</sub> (2)	P71 to P73	I <sub>OH</sub> =-0.4mA	3.0 to 5.5	V <sub>DD</sub> -0.4			
	V <sub>OH</sub> (3)		I <sub>OH</sub> =-0.2mA	2.7 to 5.5	V <sub>DD</sub> -0.4			
	V <sub>OH</sub> (4)	PWM0, PWM1	I <sub>OH</sub> =-10mA	4.5 to 5.5	V <sub>DD</sub> -1.5			
	V <sub>OH</sub> (5)	P05 (CK0 when using system clock	I <sub>OH</sub> =-1.6mA	3.0 to 5.5	V <sub>DD</sub> -0.4			
	V <sub>OH</sub> (6)	output function)	I <sub>OH</sub> =-1mA	2.7 to 5.5	V <sub>DD</sub> -0.4			
Low level output	V <sub>OL</sub> (1)	P00, P01	I <sub>OL</sub> =30mA	4.5 to 5.5			1.5	.,
voltage	V <sub>OL</sub> (2)		I <sub>OL</sub> =5mA	3.0 to 5.5			0.4	V
	V <sub>OL</sub> (3)		I <sub>OL</sub> =2.5mA	2.7 to 5.5			0.4	
	V <sub>OL</sub> (4)	Ports 0, 1, 2	I <sub>OL</sub> =10mA	4.5 to 5.5			1.5	
	V <sub>OL</sub> (5)	PWM0, PWM1 XT2	I <sub>OL</sub> =1.6mA	3.0 to 5.5			0.4	
	V <sub>OL</sub> (6)	- 12	I <sub>OL</sub> =1mA	2.7 to 5.5			0.4	
	V <sub>OL</sub> (7)	Ports 3, 7	I <sub>OL</sub> =1.6mA	3.0 to 5.5			0.4	
	V <sub>OL</sub> (8)		I <sub>OL</sub> =1mA	2.7 to 5.5			0.4	
Pull-up resistance	Rpu(1)	Ports 0, 1, 2, 3	V <sub>OH</sub> =0.9V <sub>DD</sub>	4.5 to 5.5	15	35	80	
	Rpu(2)	Port 7		2.7 to 5.5	18	50	150	kΩ
Hysteresis voltage	VHYS	RES Ports 1, 2, 3, 7		2.7 to 5.5		0.1V <sub>DD</sub>		V
Pin capacitance	СР	All pins	For pins other than that under test: VIN=VSS f=1MHz Ta=25°C	2.7 to 5.5		10		pF

### **Electrical Characteristics** at $Ta = -30^{\circ}C$ to $+70^{\circ}C$ , $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

# Serial I/O Characteristics at Ta = $-30^{\circ}$ C to $+70^{\circ}$ C, V<sub>SS</sub>1 = V<sub>SS</sub>2 = V<sub>SS</sub>3 = 0V

# 1. SIO0 Serial I/O Characteristics (Note 4-1-1)

	Parameter	Symbol	Pin/Remarks	Conditions			Speci	fication	
г -	arameter	Symbol	FINITCEINAIRS	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
	Frequency	tSCK(1)	SCK0(P12)	See Fig.9.		2			
	Low level	tSCKL(1)							-
	pulse width					1			
	High level	tSCKH(1)				1			
	pulse width				-				-
		tSCKHA(1a)		Continuous data transmission/ reception mode					
				USB nor SIO4 are not in					
				use simultaneous.		4			
				See Fig.8.					
Š				• (Note 4-1-2)					
Input clock		tSCKHA(1b)		Continuous data	2.7 to 5.5				
ndu				transmission/reception mode	2.1 10 0.0				tCY
-				USB is in use simultaneous.					
				SIO4 is not in use		7			
				simultaneous.		-			
				• See Fig.8.					
				• (Note 4-1-2)					
		tSCKHA(1c)		Continuous data transmission/					
		. ,		reception mode					
				• USB and SIO4 are in use					
				simultaneous.		9			
				See Fig.8.					
				• (Note 4-1-2)					
	Frequency	tSCK(2)	SCK0(P12)	CMOS output selected		4/3			
	Low level	tSCKL(2)		• See Fig.8.					
	pulse width	(00).12(2)					1/2		
	High level	tSCKH(2)					4.10		tSCI
	pulse width						1/2		
		tSCKHA(2a)		Continuous data transmission/					
				reception mode				tSCKH(2)	
				USB nor SIO4 are not in		tSCKH(2)		+(10/3)	
				use simultaneous.		+2tCYC		tCYC	
				CMOS output selected					
쓧				See Fig.8.					
t clock									
Itput clock		tSCKHA(2b)		Continuous data transmission/	2.7 to 5.5				
Output clock		tSCKHA(2b)		reception mode	2.7 to 5.5				
Output clock		tSCKHA(2b)		reception mode <ul> <li>USB is in use simultaneous.</li> </ul>	2.7 to 5.5	tSCKH(2)		tSCKH(2)	tov
Output clock		tSCKHA(2b)		reception mode <ul> <li>USB is in use simultaneous.</li> <li>SIO4 is not in use</li> </ul>	2.7 to 5.5	tSCKH(2) +2tCYC		+(19/3)	tCY
Output clock		tSCKHA(2b)		reception mode • USB is in use simultaneous. • SIO4 is not in use simultaneous.	2.7 to 5.5				tCY
Output clock		tSCKHA(2b)		reception mode • USB is in use simultaneous. • SIO4 is not in use simultaneous. • CMOS output selected	2.7 to 5.5			+(19/3)	tCY
Output clock				reception mode • USB is in use simultaneous. • SIO4 is not in use simultaneous. • CMOS output selected • See Fig.8.	2.7 to 5.5			+(19/3)	tCY
Output clock		tSCKHA(2b)		reception mode • USB is in use simultaneous. • SIO4 is not in use simultaneous. • CMOS output selected • See Fig.8. • Continuous data transmission/	2.7 to 5.5			+(19/3) tCYC	tCY
Output clock				reception mode • USB is in use simultaneous. • SIO4 is not in use simultaneous. • CMOS output selected • See Fig.8. • Continuous data transmission/ reception mode	2.7 to 5.5	+2tCYC		+(19/3) tCYC tSCKH(2)	tCY
Output clock				reception mode • USB is in use simultaneous. • SIO4 is not in use simultaneous. • CMOS output selected • See Fig.8. • Continuous data transmission/ reception mode • USB and SIO4 are in use	2.7 to 5.5	+2tCYC tSCKH(2)		+(19/3) tCYC tSCKH(2) +(25/3)	tCY
Output clock				reception mode • USB is in use simultaneous. • SIO4 is not in use simultaneous. • CMOS output selected • See Fig.8. • Continuous data transmission/ reception mode	2.7 to 5.5	+2tCYC		+(19/3) tCYC tSCKH(2)	tCYC

Note 4-1-1: These specifications are theoretical values. Add margin depending on its use.

Note 4-1-2: To use serial-clock-input in continuous trans/rec mode, a time from SIORUN being set when serial clock is "H" to the first negative edge of the serial clock must be longer than tSCKHA.

Continued on next page.

	_		0 mbal					Speci	ification	
	F	Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
Serial input	Da	ta setup time	tsDI(1)	SB0(P11), SI0(P11)	<ul> <li>Must be specified with respect to rising edge of SIOCLK.</li> <li>See Fig.8.</li> </ul>	2.7 to 5.5	0.03			
Serial	Da	ta hold time	thDI(1)			2.7 to 5.5	0.03			
	clock	Output delay time	tdD0(1)	SO0(P10), SB0(P11)	Continuous data transmission/reception mode (Note 4-1-3)	2.7 to 5.5			(1/3)tCYC +0.05	μs
Serial output	Input clock		tdD0(2)		Synchronous 8-bit mode     (Note 4-1-3)	2.7 to 5.5			1tCYC +0.05	
Seria	Output clock		tdD0(3)		(Note 4-1-3)	2.7 to 5.5			(1/3)tCYC +0.05	

Note 4-1-3: Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig.8.

		Demonster	Oursehal	Die (Derserlie	Conditions			Speci	ification	
		Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
	×	Frequency	tSCK(3)	SCK1(P15)	See Fig.8.		2			
	Input clock	Low level pulse width	tSCKL(3)			2.7 to 5.5	1			tCYC
clock		High level pulse width	tSCKH(3)				1			τυru
Serial clock	¥	Frequency	tSCK(4)	SCK1(P15)	CMOS output selected     See Fig.8.		2			
	Output clock	Low level pulse width	tSCKL(4)			2.7 to 5.5		1/2		
	nO	High level pulse width	tSCKH(4)					1/2		tSCK
Serial input	Da	ata setup time	tsDI(2)	SB1(P14), SI1(P14)	Must be specified with respect to rising edge of SIOCLK.	2.7 to 5.5	0.03			
Serial	Da	ata hold time	thDI(2)		• See Fig.8.	2.7 to 5.5	0.03			
Serial output	Οι	utput delay time	tdD0(4)	SO1(P13), SB1(P14)	<ul> <li>Must be specified with respect to falling edge of SIOCLK.</li> <li>Must be specified as the time to the beginning of output state change in open drain output mode.</li> <li>See Fig.8.</li> </ul>	2.7 to 5.5			(1/3)tCYC +0.05	μS

### 2. SIO1 Serial I/O Characteristics (Note 4-2-1)

Note 4-2-1: These specifications are theoretical values. Add margin depending on its use.

### 3. SIO4 Serial I/O Characteristics (Note 4-3-1)

	F	Parameter	Symbol	Pin/	Conditions			Specif	ication	1
	· - 1			Remarks		V <sub>DD</sub> [V]	min	typ	max	unit
		Frequency	tSCK(5)	SCK4(P24)	See Fig.8.		2			
		Low level pulse width	tSCKL(5)				1			
		High level pulse width	tSCKH(5)				1			
	Input clock		tSCKHA(5a)		<ul> <li>USB nor continuous data Transmission/reception mode Of SIO0 are not in use simultaneous.</li> <li>See Fig.8.</li> <li>(Note 4-3-2)</li> </ul>		4			
		tS	tSCKHA(5b)		<ul> <li>USB is in use simultaneous.</li> <li>Do not use SIO0 continuous data transmission mode at the same time.</li> <li>See Fig.8.</li> <li>(Note 4-3-2)</li> </ul>	- 2.7 to 5.5	7			tCYC
Serial clock			tSCKHA(5c)		<ul> <li>USB and continuous data transmission/ reception mode of SIO0 are in use simultaneous.</li> <li>See Fig.8.</li> <li>(Note 4-3-2)</li> </ul>		10			
Serial		Frequency	tSCK(6)	SCK4(P24)	CMOS output selected     See Fig.8		4/3			
		Low level pulse width	tSCKL(6)					1/2		tSCK
		High level pulse width	tSCKH(6)					1/2		ISON
	clock		tSCKHA(6a)		<ul> <li>USB, AIF nor continuous data transmission/reception mode of SIO0 are not in use simultaneous.</li> <li>CMOS output selected</li> <li>See Fig.8.</li> </ul>		tSCKH(6) +(5/3) tCYC		tSCKH(6) +(10/3) tCYC	
	Output clock		tSCKHA(6b)		<ul> <li>USB is in use simultaneous.</li> <li>Do not use SIO0 continuous data transmission mode at the same time.</li> <li>CMOS output selected</li> <li>See Fig8.</li> </ul>	2.7 to 5.5	tSCKH(6) +(5/3) tCYC		tSCKH(6) +(19/3) tCYC	tCYC
			tSCKHA(6c)		USB and continuous data transmission/reception mode of SIO0 are in use simultaneous.     CMOS output selected     See Fig.8.		tSCKH(6) +(5/3) tCYC		tSCKH(6) +(28/3) tCYC	
input	Da	ta setup time	tsDI(3)	SO4(P22), SI4(P23)	Must be specified with respect to rising edge of SIOCLK.     See Fig.8.	2.7 to 5.5	0.03			
Serial input	Da	ta hold time	thDI(3)			2.7 to 5.5	0.03			μs

Note 4-3-1: These specifications are theoretical values. Add margin depending on its use.

Note 4-3-2: To use serial-clock-input in continuous trans/rec mode, a time from SI4RUN being set when serial clock is "H" to the first negative edge of the serial clock must be longer than tSCKHA.

Continued on next page.

Con	tinued from preceding		Pin/				Speci	fication	
	Parameter	Symbol	Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
Serial output	Output delay time	tdD0(5)	SO4(P22), SI4(P23)	<ul> <li>Must be specified with respect to rising edge of SIOCLK.</li> <li>Must be specified as the time to the beginning of output state change in open drain output mode.</li> <li>See Fig.8.</li> </ul>	2.7 to 5.5			(1/3)tCYC +0.05	μS

# **Pulse Input Conditions** at Ta = -30 °C to +70 °C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0$ V

Description	0 set et					Specific	ation	
Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
High/low level pulse width	tP1H(1) tP1L(1)	INT0(P70), INT1(P71), INT2(P72), INT4(P20 to P23), INT5(P24 to P27)	<ul> <li>Interrupt source flag can be set.</li> <li>Event inputs for timer 0 or 1 are enabled.</li> </ul>	2.7 to 5.5	1			
	tPIH(2) tPIL(2)	INT3(P73) when noise filter time constant is 1/1	<ul> <li>Interrupt source flag can be set.</li> <li>Event inputs for timer 0 are enabled.</li> </ul>	2.7 to 5.5	2			tCYC
	tPIH(3) tPIL(3)	INT3(P73) when noise filter time constant is 1/32	<ul> <li>Interrupt source flag can be set.</li> <li>Event inputs for timer 0 are enabled.</li> </ul>	2.7 to 5.5	64			
-	tPIH(4) tPIL(4)	INT3(P73) when noise filter time constant is 1/128	<ul> <li>Interrupt source flag can be set.</li> <li>Event inputs for timer 0 are enabled.</li> </ul>	2.7 to 5.5	256			
	tPIL(5)	RMIN(P73)	Recognized by the infrared remote controller receiver circuit as a signal.	2.7 to 5.5	4			RMC K (Note 5- 1)
	tPIL(6)	RES	Resetting is enabled.	2.7 to 5.5	200			μS

Note5-1: Represents the period of the reference clock (1 tCYC to 128 tCYC or the source frequency of the subclock) for the infrared remote controller receiver circuit.

### **AD Converter Characteristics** at Ta = -30°C to +70°C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0$ V

<12-bits AD Converter Mode>

Descenter	O week al	Dire (Derroerloe	Conditions	_		Specif	ication	
Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
Resolution	Ν	AN0(P00) to		3.0 to 5.5		12		bit
Absolute accuracy	ET	AN8(P70)	(Note 6-1)	3.0 to 5.5			±16	LSB
Conversion time	TCAD	· · · ·	See conversion time calculation	4.0 to 5.5	32		115	
		AN9(P71) AN10(XT1)	formulas. (Note 6-2)	3.0 to 5.5	64		115	μS
Analog input voltage range	VAIN	AN11(XT2)		3.0 to 5.5	V <sub>SS</sub>		V <sub>DD</sub>	V
Analog port input	IAINH		VAIN=V <sub>DD</sub>	3.0 to 5.5			1	
current	IAINL		VAIN=V <sub>SS</sub>	3.0 to 5.5	-1			μA

#### <8-bits AD Converter Mode>

Descenter	O week al	Die /Deeserie	arks Conditions			Specif	fication	
Parameter	Symbol	Pin/Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
Resolution	Ν	AN0(P00) to		3.0 to 5.5		8		bit
Absolute accuracy	ET	AN7(P07)	(Note 6-1)	3.0 to 5.5			±1.5	LSB
Conversion time	TCAD	AN8(P70)	See conversion time calculation	4.0 to 5.5	20		90	
		AN9(P71) AN10(XT1) AN11(XT2)	formulas. (Note 6-2)	3.0 to 5.5	40		90	μS
Analog input voltage range	VAIN			3.0 to 5.5	V <sub>SS</sub>		V <sub>DD</sub>	V
Analog port input	IAINH		VAIN=V <sub>DD</sub>	3.0 to 5.5			1	
current	IAINL		VAIN=V <sub>SS</sub>	3.0 to 5.5	-1			μA

Conversion time calculation formulas:

12-bits AD Converter Mode: TCAD (Conversion time) =  $((52/(AD \text{ division ratio}))+2) \times (1/3) \times tCYC$ 8-bits AD Converter Mode: TCAD (Conversion time) =  $((32/(AD \text{ division ratio}))+2) \times (1/3) \times tCYC$ 

<Recommended Operating Conditions>

External	Supply Voltage	Range System Clock		AD Frequency	Conversion Time (TCAD)[µs]		
oscillator FmCF[MHz]	Range V <sub>DD</sub> [V]	Division (SYSDIV)	tCYC [ns]	Division Ratio (ADDIV)	12-bit AD	8-bit AD	
10	4.0 to 5.5	1/1	250	1/8	34.8	21.5	
12	3.0 to 5.5	1/1	250	1/16	69.5	42.8	

Note 6-1: The quantization error (±1/2LSB) must be excluded from the absolute accuracy. The absolute accuracy must be measured in the microcontroller's state in which no I/O operations occur at the pins adjacent to the analog input channel.

Note 6-2: The conversion time refers to the period from the time an instruction for starting a conversion process till the time the conversion results register(s) are loaded with a complete digital conversion value corresponding to the analog input value.

The conversion time is 2 times the normal-time conversion time when:

- The first AD conversion is performed in the 12-bit AD conversion mode after a system reset.
- The first AD conversion is performed after the AD conversion mode is switched from 8-bit to 12-bit conversion mode.

# **Consumption Current Characteristics** at $Ta = -30^{\circ}C$ to $+70^{\circ}C$ , $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Parameter	Symbol	Pin/	Conditions			Specific	cation	
Falameter	Symbol	Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
Normal mode consumption current	IDDOP(1)	V <sub>DD</sub> 1 =V <sub>DD</sub> 2 =V <sub>DD</sub> 3	FmCF=12MHz ceramic oscillation mode     FsX'tal=32.768kHz crystal oscillation mode     System clock set to 12MHz side	4.4 to 5.5		9.8	24	
(Note 7-1)	IDDOP(2)		<ul> <li>Internal PLL oscillation stopped</li> <li>Internal RC oscillation stopped</li> <li>USB circuit stopped</li> <li>1/1 frequency division ration</li> </ul>	3.0 to 3.6		5.6	14	
	IDDOP(3)		FmCF=12MHz ceramic oscillation mode     FsX'tal=32.768kHz crystal oscillation mode     System clock set to 12MHz side     Internal PLL oscillation mode	4.4 to 5.5		14	34	
	IDDOP(4)		Internal PEL Oscillation Hode     Internal RC oscillation stopped     USB circuit operation mode     1/1 frequency division ration	3.0 to 3.6		7.7	19	mA
	IDDOP(5)		FmCF=12MHz ceramic oscillation mode     FsX'tal=32.768kHz crystal oscillation mode	4.4 to 5.5		6.1	14	
	IDDOP(6)		System clock set to 6MHz side     Internal RC oscillation stopped	3.0 to 3.6		3.7	8.5	
	IDDOP(7)	_	1/2 frequency division ration	2.7 to 3.0		3.0	6.7	
	IDDOP(8)	_	<ul> <li>FmCF=0MHz (oscillation stopped)</li> <li>FsX'tal=32.768kHz crystal oscillation mode</li> </ul>	4.4 to 5.5		0.63	3.0	
	IDDOP(9)	_	System clock set to internal RC oscillation	3.0 to 3.6		0.35	1.6	
	IDDOP(10)	_	1/2 frequency division ration     FmCF=0MHz (oscillation stopped)	2.7 to 3.0		0.30	1.3	
		_	FsX'tal=32.768kHz crystal oscillation mode	4.4 to 5.5		39	150	
	IDDOP(12)	-	System clock set to 32.768kHz side     Internal RC oscillation stopped	3.0 to 3.6		17	58	μA
	- ( - /		1/2 frequency division ration	2.7 to 3.0		14	43	
HALT mode consumption current (Note 7-1)	IDDHALT(1)	V <sub>DD</sub> 1 =V <sub>DD</sub> 2 =V <sub>DD</sub> 3	HALT mode     FmCF=12MHz ceramic oscillation mode     FsX'tal=32.768kHz crystal oscillation mode     System clock set to 12MHz side	4.4 to 5.5		4.9	12	
	IDDHALT(2)		<ul> <li>Internal PLL oscillation stopped</li> <li>Internal RC oscillation stopped</li> <li>USB circuit stopped</li> <li>1/1 frequency division ration</li> </ul>	3.0 to 3.6		2.6	6.3	
	IDDHALT(3)		HALT mode     FmCF=12MHz ceramic oscillation mode     FsX'tal=32.768kHz crystal oscillation mode     System clock set to 12MHz side	4.4 to 5.5		8.9	23	mA
	IDDHALT(4)		<ul> <li>Internal PLL oscillation mode</li> <li>Internal RC oscillation stopped</li> <li>USB circuit operation mode</li> <li>1/1 frequency division ration</li> </ul>	3.0 to 3.6		4.6	12	
	IDDHALT(5)		HALT mode     FmCF=12MHz ceramic oscillation mode	4.4 to 5.5		3.0	7.2	
	IDDHALT(6)	1	<ul> <li>FsX'tal=32.768kHz crystal oscillation mode</li> <li>System clock set to 6MHz side</li> </ul>	3.0 to 3.6		1.6	3.8	
	IDDHALT(7)	4	Internal RC oscillation stopped					

Note 7-1: The consumption current value includes none of the currents that flow into the output Tr and internal pull-up resistors.

Continued on next page.

Description		Pin/				ation		
Parameter	Symbol	Remarks	Conditions	V <sub>DD</sub> [V]	min	typ	max	unit
HALT mode	IDDHALT(8)	V <sub>DD</sub> 1	HALT mode	4.4 to 5.5		0.37	1.8	
consumption current (Note 7-1)	IDDHALT(9)	=V <sub>DD</sub> 2 =V <sub>DD</sub> 3	FmCF=0MHz (oscillation stopped)     FsX'tal=32.768kHz crystal oscillation mode	3.0 to 3.6		0.18	0.83	mA
	IDDHALT(10)		<ul> <li>System clock set to internal RC oscillation</li> <li>1/2 frequency division ration</li> </ul>	2.7 to 3.0		0.15	0.62	
	IDDHALT(11)		HALT mode     FmCF=0MHz (oscillation stopped)	4.4 to 5.5		24	93	
	IDDHALT(12)		FsX'tal=32.768kHz crystal oscillation mode     System clock set to 32.768kHz side     Internal RC oscillation stopped     1/2 frequency division ration	3.0 to 3.6		7.9	33	
	IDDHALT(13)			2.7 to 3.0		5.8	22	
HOLD mode	IDDHOLD(1)	V <sub>DD</sub> 1	HOLD mode	4.4 to 5.5		0.08	24	μA
consumption current	IDDHOLD(2)		• CF1=V <sub>DD</sub> or open (External clock mode)	3.0 to 3.6		0.03	11	
	IDDHOLD(3)			2.7 to 3.0		0.02	9.6	
Timer HOLD	IDDHOLD(4)	V <sub>DD</sub> 1	Timer HOLD mode	4.4 to 5.5		19	77	
mode	IDDHOLD(5)		• CF1=V <sub>DD</sub> or open (External clock mode)	3.0 to 3.6		5.1	23	
consumption current	IDDHOLD(6)		<ul> <li>FsX'tal=32.768kHz crystal oscillation mode</li> </ul>	2.7 to 3.0		3.3	14	

Note 7-1: The consumption current value includes none of the currents that flow into the output Tr and internal pull-up resistors.

### USB Characteristics and Timing at Ta = $0^{\circ}$ C to + $70^{\circ}$ C, V<sub>SS</sub>1 = V<sub>SS</sub>2 = V<sub>SS</sub>3 = 0V

Dementer	Querrahad	Oraditions	Specif		fication	
Parameter	Symbol	Conditions		typ	max	unit
High level output	High level output         VOH(USB)         • 15kΩ±5% to GND		2.8		3.6	V
Low level output	V <sub>OL(USB)</sub>	• 1.5kΩ±5% to 3.6 V	0.0		0.3	V
Output signal crossover voltage	V <sub>CRS</sub>		1.3		2.0	V
Differential input sensitivity	V <sub>DI</sub>	•  (D+)–(D–)	0.2			V
Differential input common mode range	V <sub>CM</sub>		0.8		2.5	V
High level input	V <sub>IH(USB)</sub>		2.0			V
Low level input	V <sub>IL(USB)</sub>				0.8	V
USB data rise time	<sup>t</sup> R	• R <sub>S</sub> =27 to 33Ω, CL=50pF • V <sub>DD</sub> 3=3.0 to 3.6V	4		20	ns
USB data fall time t <sub>F</sub> • R <sub>S</sub> =27 to 33Ω, CL=50pF • V <sub>DD</sub> 3=3.0 to 3.6V			4		20	ns

# **F-ROM Programming Characteristics** at $Ta = +10^{\circ}C$ to $+55^{\circ}C$ , $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Deremeter	Symbol	Pin	Conditions		Specification					
Parameter	Parameter Symbol Pin Conditions		Conditions	V <sub>DD</sub> [V]	min	typ	max	unit		
Onboard programming current	IDDFW(1)	V <sub>DD</sub> 1	Excluding power dissipation in the microcontroller block	3.0 to 5.5		5	10	mA		
Programming	tFW(1)		Erase operation	2.04-5.5		20	30	ms		
time	tFW(2)		Write operation	3.0 to 5.5		40	60	μs		

### **Characteristics of a Sample Main System Clock Oscillation Circuit**

Given below are the characteristics of a sample main system clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 1 Characteristics of a Sample Main System Clock Oscillator Circuit with a Ceramic Oscillator at  $Ta = 0^{\circ}C$  to  $+70^{\circ}C$ 

Nominal	Vendor		Circuit Constant			Operating Voltage				
Frequency	Name	Oscillator Name	C1	C2	Rd1	Range	typ	max	Remarks	
			[pF]	[pF]	[Ω]	[V]	[ms]	[ms]		
6MHz	MURATA	CSTCR6M00G15L**-R0	(39)	(39)	680	2.7 to 5.5	0.05	0.50		
8MHz	MURATA	CSTCE8M00G15L**-R0	(33)	(33)	220	3.0 to 5.5	0.05	0.50		
10MHz	MURATA	CSTCE10M0G15L**-R0	(33)	(33)	220	3.0 to 5.5	0.05	0.50	Built-in C1, C2	
12MHz	MURATA	CSTCE12M0G15L**-R0	(33)	(33)	330	3.0 to 5.5	0.05	0.50		

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after  $V_{DD}$  goes above the operating voltage lower limit (see Figure 4).

### **Characteristics of a Sample Subsystem Clock Oscillator Circuit**

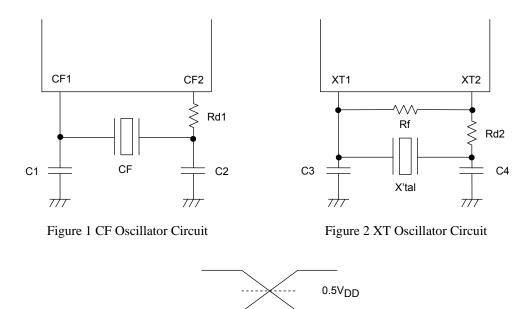
Given below are the characteristics of a sample subsystem clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

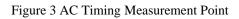
Table 2 Cha	Table 2 Characteristics of a Sample Subsystem Clock Oscinator Circuit with a CF Oscinator									
Nominal	Vendor	Os sillatas Nama		Circuit (	Constant		Operating Voltage		llation tion Time	Demedia
Frequency	Name	Oscillator Name	C3	C4	Rf	Rd2	Range	typ	max	Remarks
			[pF]	[pF]	[Ω]	[Ω]	[V]	[s]	[s]	
32.768kHz	EPSON TOYOCOM	MC-306	18	18	OPEN	560k	2.7 to 5.5	1.1	3.0	Applicable CL value=12.5pF

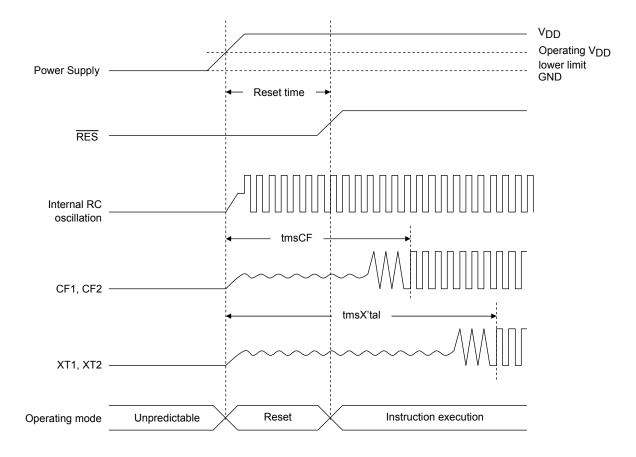
Table 2 Characteristics of a Sample Subsystem Clock Oscillator Circuit with a CF Oscillator

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after the instruction for starting the subclock oscillation circuit is executed and to the time interval that is required for the oscillation to get stabilized after the HOLD mode is reset (see Figure 4).

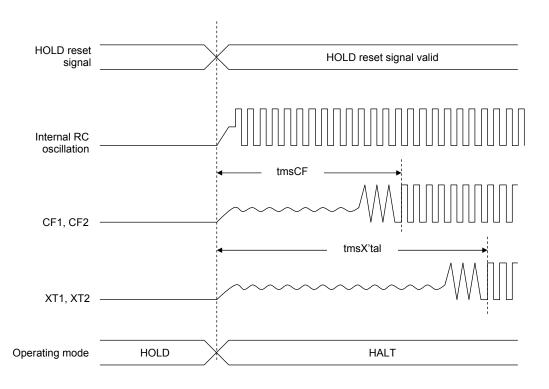
Note: The components that are involved in oscillation should be placed as close to the IC and to one another as possible because they are vulnerable to the influences of the circuit pattern.





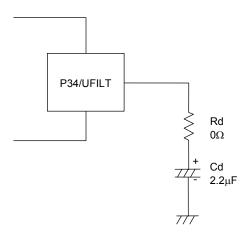


Reset Time and Oscillation Stabilization Time

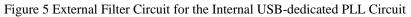


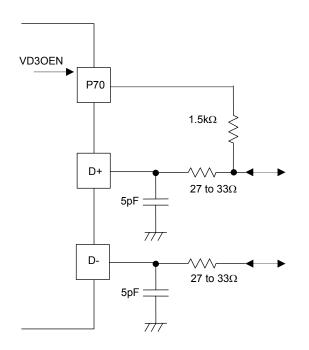
HOLD Reset Signal and Oscillation Stabilization Time

Figure 4 Oscillation Stabilization Time



When using the internal PLL circuit to generate the 48 MHz clock for USB, it is necessary to connect a filter circuit such as that shown to the left to the P34/UFILT pin.

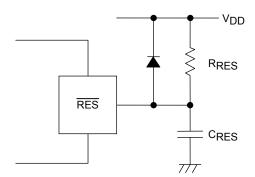




Note:

It's necessary to adjust the Circuit Constant of the USB Port Peripheral Circuit each mounting board. Make the D+ Pull-up resistors available to control on/off according to the Vbus.

Figure 6 USB Port Peripheral Circuit



Note:

Determine the value of CRES and RRES so that the reset signal is present for a period of 200µs after the supply voltage goes beyond the lower limit of the IC's operating voltage.



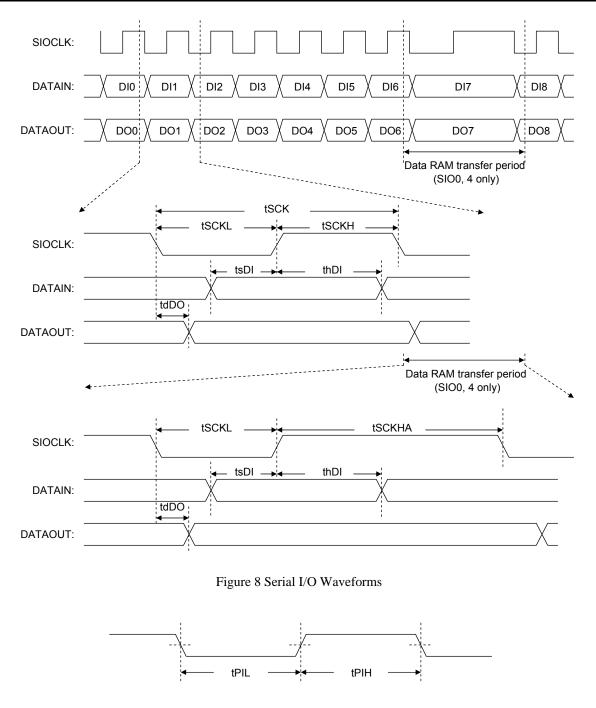


Figure 9 Pulse Input Timing Signal Waveform

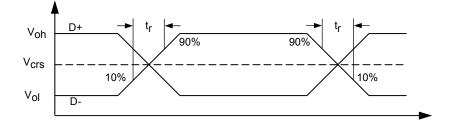


Figure 10 USB Data Signal Timing and Voltage Level

#### **ORDERING INFORMATION**

Device	Package	Shipping (Qty / Packing)			
LC87F1A32AUWA-2H	SPQFP-48 / SQFP-48 (Pb-Free / Halogen Free)	2500 / Tray JEDEC			

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